PATENT ASSIGNMENT COVER SHEET

Electronic Version v1.1
Stylesheet Version v1.2

EPAS ID: PAT6800649

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT

CONVEYING PARTY DATA

Name	Execution Date
ROBERT J. STACEY	04/08/2020
CARLOS CORDEIRO	04/08/2020
CHITTABRATA GHOSH	12/28/2020
DANIEL F. BRAVO	04/10/2020
DIBAKAR DAS	06/30/2021
LAURENT CARIOU	05/26/2021
PO-KAI HUANG	04/08/2020
XIAOGANG CHEN	06/16/2021
ARIK KLEIN	04/12/2020
DANNY ALEXANDER	04/13/2020
CHENG CHEN	04/08/2020

RECEIVING PARTY DATA

Name:	INTEL CORPORATION
Street Address:	2200 MISSION COLLEGE BLVD.
City:	SANTA CLARA
State/Country:	CALIFORNIA
Postal Code:	95054

PROPERTY NUMBERS Total: 1

Property Type	Number
Application Number:	17329763

CORRESPONDENCE DATA

Fax Number:

Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.

Phone: 612-373-6900
Email: request@slwip.com
Correspondent Name: SCHWEGMAN, LUNDBERG & WOESSNER/INTEL
Address Line 1: PO BOX 2938
Address Line 4: MINNEAPOLIS, MINNESOTA 55402

ATTORNEY DOCKET NUMBER:	1884.A20US2
NAME OF SUBMITTER:	NANCY CUNDALL
SIGNATURE:	/Nancy Cundall/
DATE SIGNED:	07/07/2021

Total Attachments: 34

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Intel Docket No.: ***AC8581-US***
SLW Reference No.: (AC8581-US)
1884.A20US1

ASSIGNMENT

In consideration of good and valuable consideration, the receipt of which is hereby acknowledged, we, the undersigned inventor(s):

<Robert J. Stacey, Carlos Cordeiro, Chittabrata Ghosh, Daniel F. Bravo, Dibakar Das, Laurent Cariou, Po-Kai Huang, Xiaogang Chen, Arik Klein, Danny Alexander, Cheng Chen>

hereby sell, assign, and transfer to:

Intel Corporation

a corporation of Delaware, having a principal place of business at 2200 Mission College Boulevard, Santa Clara, California, 95054 USA ("Assignee"), and its successors, assigns, and legal representatives, the entire right, title, and interest for the United States and all other countries, in and to any and all inventions and improvements that are disclosed in the application for the patent entitled:

MULTI-LINK DISCOVERY SIGNALING IN EXTREMELY HIGH THROUGHPUT (EHT) SYSTEMS

(I hereby authorize and request any attorney having appropriate authority from the assignee to insert on the designated lines below, the filing date and application number of said application when known.)

which was filed on **March 20, 2020** as

United States of America Application Number **16/825,028**

which has been executed by the undersigned prior hereto or concurrently herewith on the date(s) indicated below,

and in and to said application and all Additional Applications, and all other patent applications that have been or shall be filed in the United States and all other countries and international filing offices on any of said inventions and improvements; and in and to all original and reissued patents that have been or shall be issued in the United States and all other countries and international filing offices on said inventions and improvements; and in and to all rights of priority resulting from the filing of said applications; as used herein "Additional Applications" includes but is not limited to design, utility, utility model, divisional, continuing, continuation-in-part, substitute, renewal, reissue, and national phase applications on said inventions and improvements;

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/rjstacey/ Robert J. Stacey	4/8/2020 Date Signed
Carlos Cordeiro	Date Signed
Chittabrata Ghosh	Date Signed
Daniel F. Bravo	Date Signed
Dibakar Das	Date Signed
Laurent Cariou	Date Signed
Po-Kai Huang	Date Signed

Xiaogang Chen	Date Signed
Arik Klein	Date Signed
Danny Alexander	Date Signed
Cheng Chen	Date Signed

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Robert J. Stacey	Date Signed
	April 08, 2020
Carlos Cordeiro	Date Signed
Chittabrata Ghosh	Date Signed
Daniel F. Bravo	Date Signed
Dibakar Das	Date Signed
Laurent Cariou	Date Signed
Po-Kai Huang	Date Signed

Xiaogang Chen	Date Signed
Arik Klein	Date Signed
Danny Alexander	Date Signed
Cheng Chen	Date Signed

Intel Docket No.: AC8581-US
SLW Reference No.: (AC8581-US)
1884.A20US1

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Robert J. Stacey	Date Signed
Carlos Cordeiro	Date Signed
Chittabrata Ghosh	12/28/2020 Date Signed
Daniel F. Bravo	Date Signed
Dibakar Das	Date Signed
Laurent Cariou	Date Signed
Po-Kai Huang	Date Signed

Xiaogang Chen — Date Signed

Arik Klein — Date Signed

Danny Alexander — Date Signed

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Robert J. Stacey	Date Signed
Carlos Cordeiro	Date Signed
Chittabrata Ghosh	Date Signed
Daniel F. Bravo	4-10-2020 Date Signed
Dibakar Das	Date Signed
Laurent Cariou	Date Signed
Po-Kai Huang	Date Signed

Xiaogang Chen	Date Signed
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Robert J. Stacey	Date Signed
Carlos Cordeiro	Date Signed
Chittabrata Ghosh	Date Signed
Daniel F. Bravo	Date Signed
Dibakar Das	06/30/21 Date Signed
Laurent Cariou	Date Signed
Po-Kai Huang	Date Signed

Xiaogang Chen	Date Signed
Arik Klein	Date Signed
Danny Alexander	Date Signed
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Carlos Cordeiro	Date Signed
Chittabrata Ghosh	Date Signed
Daniel F. Bravo	Date Signed
Dibakar Das	Date Signed
Laurent Cariou	05 - 26 - 2021 Date Signed
Po-Kai Huang	Date Signed

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Carlos Cordeiro — Date Signed

Chittabrata Ghosh — Date Signed

Daniel F. Bravo — Date Signed

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Laurent Cariou — Date Signed

04/08/2020

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6/16/21

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Cheng Chen — Date Signed

ASSIGNMENT

In consideration of good and valuable consideration, the receipt of which is hereby acknowledged, we, the undersigned inventor(s):

<Robert J. Stacey, Carlos Cordeiro, Chittabrata Ghosh, Daniel F. Bravo, Dibakar Das, Laurent Cariou, Po-Kai Huang, Xiaogang Chen, Arik Klein, Danny Alexander, Cheng Chen>

hereby sell, assign, and transfer to:

Intel Corporation

a corporation of Delaware, having a principal place of business at 2200 Mission College Boulevard, Santa Clara, California, 95054 USA ("Assignee"), and its successors, assigns, and legal representatives, the entire right, title, and interest for the United States and all other countries, in and to any and all inventions and improvements that are disclosed in the application for the patent entitled:

MULTI-LINK DISCOVERY SIGNALING IN EXTREMELY HIGH THROUGHPUT (EHT) SYSTEMS

(I hereby authorize and request any attorney having appropriate authority from the assignee to insert on the designated lines below, the filing date and application number of said application when known.)

which was filed on **March 20, 2020** as

United States of America Application Number **16/825,028**

which has been executed by the undersigned prior hereto or concurrently herewith on the date(s) indicated below,

and in and to said application and all Additional Applications, and all other patent applications that have been or shall be filed in the United States and all other countries and international filing offices on any of said inventions and improvements; and in and to all original and reissued patents that have been or shall be issued in the United States and all other countries and international filing offices on said inventions and improvements; and in and to all rights of priority resulting from the filing of said applications; as used herein "Additional Applications" includes but is not limited to design, utility, utility model, divisional, continuing, continuation-in-part, substitute, renewal, reissue, and national phase applications on said inventions and improvements;

and agree that said Assignee may apply for and receive a patent or patents for said inventions and improvements in its own name; and that, when requested, without charge to, but at the expense of, said Assignee, its successors, assigns, and legal representatives, to carry out in good faith the intent and purpose of this Assignment, the undersigned will execute

all Additional Applications, and all other patent applications on any and all said inventions and improvements; execute all rightful oaths, assignments, powers of attorney, and other papers; communicate to said Assignee, its successors, assigns, and legal representatives all facts known to the undersigned relating to said inventions and improvements and the history thereof; and generally assist said Assignee, its successors, assigns, or legal representatives in securing and maintaining proper patent protection for said inventions and improvements and for vesting title to said inventions and improvements, and all applications for patents and all patents on said improvements, in said Assignee, its successors, assigns, and legal representatives; and

covenant with said Assignee, its successors, assigns, and legal representatives that no assignment, grant, mortgage, license, or other agreement affecting the rights and property herein conveyed has been made to others by the undersigned, and that full right to convey the same as herein expressed is possessed by the undersigned.

Robert J. Stacey	Date Signed
Carlos Cordeiro	Date Signed
Chittabrata Ghosh	Date Signed
Daniel F. Bravo	Date Signed
Dibakar Das	Date Signed
Laurent Cariou	Date Signed
Po-Kai Huang	Date Signed

Xiaogang Chen	Date Signed
Arik Klein	April 12th 2020 Date Signed
Danny Alexander	Date Signed
Cheng Chen	Date Signed

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Xiaogang Chen — Date Signed

Arik Klein — Date Signed

Danny Alexander — Date Signed

Cheng Chen — 04/08/2020
Date Signed